EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	190740	"438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 10:43
L2	1118	L1 and (pvd or (vapor same deposition)) and (position or align or alignment) same (wafer or layer) and (resist or photoresist) and (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:33
L3	171	L2 and lithographic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:37
L4	61	L3 and (position or align or alignment) same (shift or move or movement or change or alter or alteration)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:23
L5	54	L4 and thin same film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:43
L6	2	("20050181546").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/26 11:53
L7	7	L3 and (position or align or alignment) same (shift or move or movement or change or alter or alteration) same (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 11:59
L8	3	(US-20040197939-$ or US-20040058540-$ or US-20030064422-$).did.	US-PGPUB	OR	ON	2006/09/26 11:59

L9	3	L8 and (pvd or (vapor same deposition)) and (position or align or alignment) same (wafer or layer) and (resist or photoresist) and (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:52
L10	3	L8 and (position or align or alignment) same (shift or move or movement or change or alter or alteration)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:23
L11	3	L10 and (pvd or (vapor same deposition))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:39
L12	3	L8 and (pvd or (vapor same deposition))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:28
L13	3	L12 and deposition	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:39
L14	3	L11 and thin same film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 12:48
L15	3	L8 and thin same film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:35
L16	2	L8 and (pvd or (vapor same deposition)) and (position or align or alignment) same (wafer or layer) and (resist or photoresist) and (formula or equation or algorith$4) and thin same film and deposition and (pvd or cvd or pecvd)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:39

L17	3	L8 and (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:43
L18	2	L8 and (thin same film) same (resist or photoresist)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:35
L19	2	L18 and lithographic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:37
L20	2	L19 and (pvd or (vapor same deposition))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:52
L21	2	L20 and (pvd or (vapor same deposition)) and (position or align or alignment) same (wafer or layer) and (resist or photoresist) and (formula or equation or algorith$4) and thin same film and deposition and (pvd or cvd or pecvd)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:40
L22	3	L8 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:48
L23	3	L8 and (computer or control$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:17
L24	1	L8 and (computer or control$4) same (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:50

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L25	3	L23 and (pvd or (vapor same deposition))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 13:54
L26	2	L23 and (pvd or (vapor same deposition)) and (program or memory)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 14:14
L34	2	L8 and center	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:21
L35	2	L8 and rotation$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:23
L36	2	L8 and (rotation$3 or rotate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:26
L37	2	L8 and (rotation$3 or rotat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:29
L38	3	L8 and (remov$4 or etch$4) and layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:33
L39	3	L8 and (remov$4 or etch$4) and layer and mark$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:50

L40	3	L8 and (material or layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:51
L41	3	L8 and (insulat$4 or conduct$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:52
L42	1	L8 and (insulat$4 or conduct$4) and (metal or metallic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:57
L43	2	L8 and (ccd or camera)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/26 16:58
S69	21788	438/6,10,104,107,108,109,110,111, 112,113,114,118,121,122,123,128, 129,135,142,145,149,151,157,176, 478,184,193,195,196,197,198,200, 201,202,203,206,207,209,210,211, 218,237,165,294,308,337,353,378, 401,410.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 08:38
S70	182273	"438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/13 08:38
S71	23457	438/6,10,104,107,108,109,110,111, 112,113,114,118,121,122,123,128, 129,135,142,145,149,151,157,176, 478,184,193,195,196,197,198,200, 201,202,203,206,207,209,210,211, 218,237,165,294,308,337,353,378, 401,410.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 21:02
S72	190610	"438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 21:13

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S73	1118	S72 and (pvd or (vapor same deposition)) and (position or align or alignment) same (wafer or layer) and (resist or photoresist) and (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 23:32
S74	171	S73 and lithographic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 23:33
S75	61	S74 and (position or align or alignment) same (shift or move or movement or change or alter or alteration)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 23:36
S76	54	S75 and thin same film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 23:35
S77	7	S74 and (position or align or alignment) same (shift or move or movement or change or alter or alteration) same (formula or equation or algorith$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 23:36
S78	3	(US-20040197939-$ or US-20040058540-$ or US-20030064422-$).did.	US-PGPUB	OR	ON	2006/09/26 00:26